

FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = 100V$
- Lower $R_{DS(ON)}$: 0.176 Ω (Typ.)

 $BV_{DSS} = 100 V$ $R_{DS(on)} = 0.22 \Omega$ $I_D = 2.3 A$ **SOT-223**

1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	100	V
I_D	Continuous Drain Current ($T_A=25^\circ C$)	2.3	A
	Continuous Drain Current ($T_A=70^\circ C$)	1.85	
I_{DM}	Drain Current-Pulsed .. ζ	18	A
V_{GS}	Gate-to-Source Voltage .. ζ	10	V
E_{AS}	Single Pulsed Avalanche Energy .. \dot{e}	105	mJ
I_{AR}	Avalanche Current .. ζ	2.3	A
E_{AR}	Repetitive Avalanche Energy .. ζ	0.27	mJ
dv/dt	Peak Diode Recovery dv/dt .. \dot{e}	6.5	V/ns
P_D	Total Power Dissipation ($T_A=25^\circ C$) *	2.7	W
	Linear Derating Factor *	0.022	W/C
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +150	$^\circ C$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient *	--	46.3	$^\circ C/W$

* When mounted on the minimum pad size recommended (PCB Mount).

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Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	100	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
$\Delta\text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.09	--	$^\circ\text{C}$	$\text{I}_D=250\mu\text{A}$ See Fig 7
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	1.0	--	2.0	V	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	$\text{V}_{\text{GS}}=20\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100		$\text{V}_{\text{GS}}=-20\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	10	μA	$\text{V}_{\text{DS}}=100\text{V}$
		--	--	100		$\text{V}_{\text{DS}}=80\text{V}, \text{T}_C=125^\circ\text{C}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	0.22	Ω	$\text{V}_{\text{GS}}=5\text{V}, \text{I}_D=1.15\text{A}$ ④
g_{fs}	Forward Transconductance	--	4.6	--	S	$\text{V}_{\text{DS}}=40\text{V}, \text{I}_D=1.15\text{A}$ ④
C_{iss}	Input Capacitance	--	340	440	pF	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	90	115		
C_{rss}	Reverse Transfer Capacitance	--	39	50		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	5	20	ns	$\text{V}_{\text{DD}}=50\text{V}, \text{I}_D=9.2\text{A}, \text{R}_G=9 \Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	--	10	30		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	19	50		
t_f	Fall Time	--	9	30		
Q_g	Total Gate Charge	--	10.2	15	nC	$\text{V}_{\text{DS}}=80\text{V}, \text{V}_{\text{GS}}=5\text{V}, \text{I}_D=9.2\text{A}$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	1.7	--		
Q_{gd}	Gate-Drain("Miller") Charge	--	6.0	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_s	Continuous Source Current	--	--	2.3	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	18		
V_{SD}	Diode Forward Voltage ④	--	--	1.5	V	$\text{T}_J=25^\circ\text{C}, \text{I}_s=2.3\text{A}, \text{V}_{\text{GS}}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	98	--	ns	$\text{T}_J=25^\circ\text{C}, \text{I}_F=9.2\text{A}$ $d\text{I}/dt=100\text{A}/\mu\text{s}$
Q_{rr}	Reverse Recovery Charge	--	0.34	--		

Notes :

- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ② $L=30\text{mH}, \text{I}_{\text{AS}}=2.3\text{A}, \text{V}_{\text{DD}}=25\text{V}, \text{R}_G=27\Omega, \text{Starting } \text{T}_J=25^\circ\text{C}$
- ③ $\text{I}_{\text{SD}} \leq 9.2\text{A}, \text{di}/\text{dt} \leq 300\text{A}/\mu\text{s}, \text{V}_{\text{DD}} \leq \text{BV}_{\text{DSS}}, \text{Starting } \text{T}_J=25^\circ\text{C}$
- ④ Pulse Test : Pulse Width = 250 μs , Duty Cycle $\leq 2\%$
- ⑤ Essentially Independent of Operating Temperature

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Fig 1. Output Characteristics

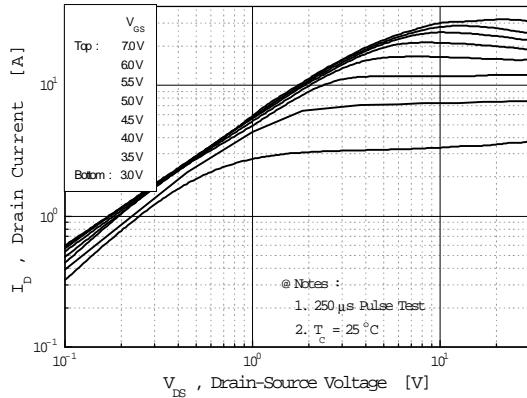


Fig 2. Transfer Characteristics

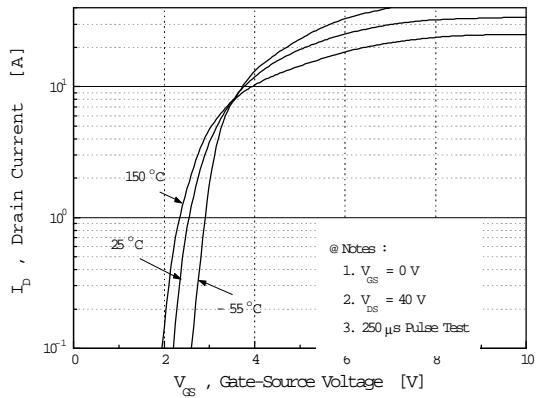


Fig 3. On-Resistance vs. Drain Current

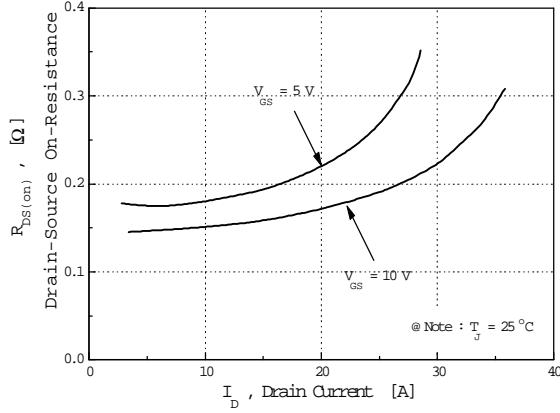


Fig 4. Source-Drain Diode Forward Voltage

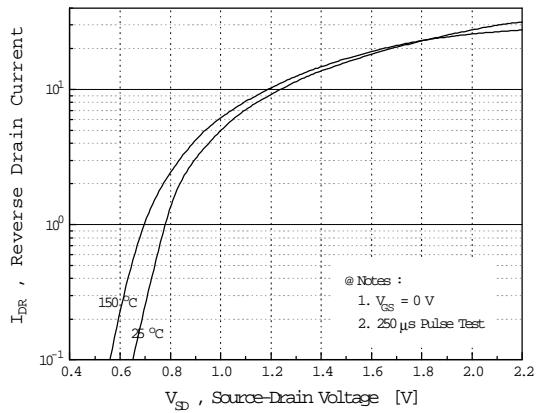


Fig 5. Capacitance vs. Drain-Source Voltage

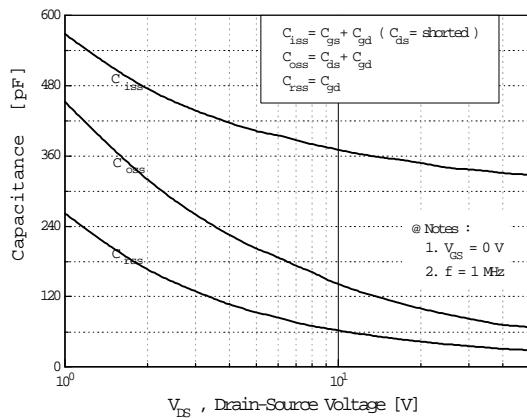
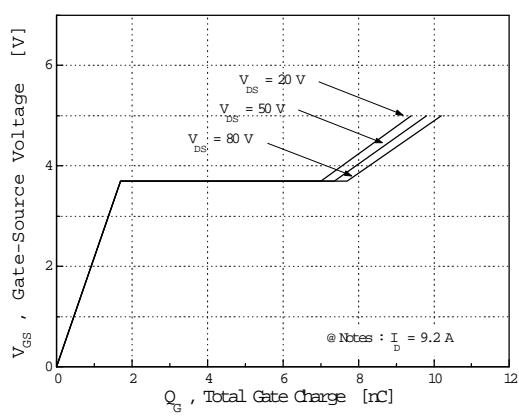
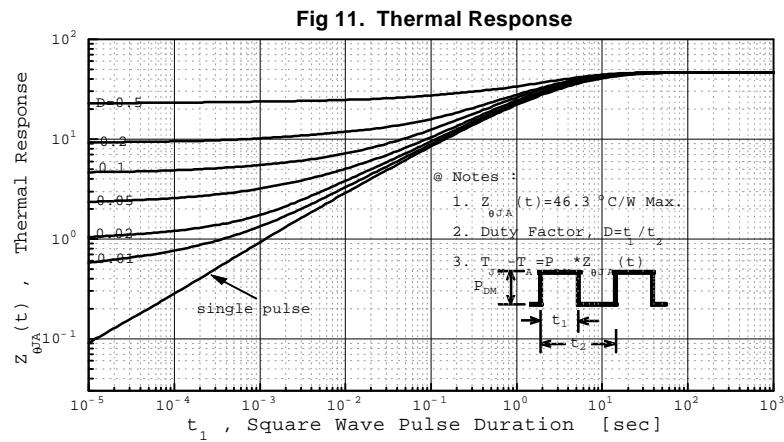
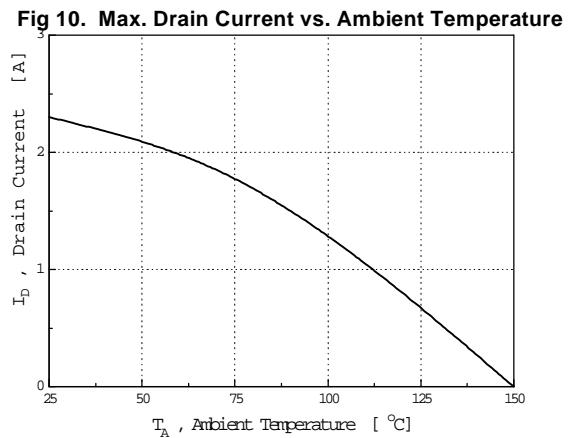
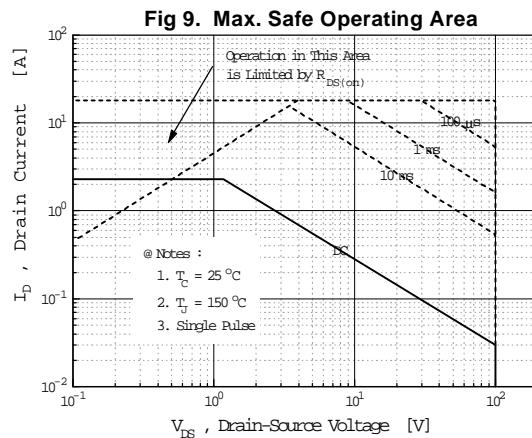
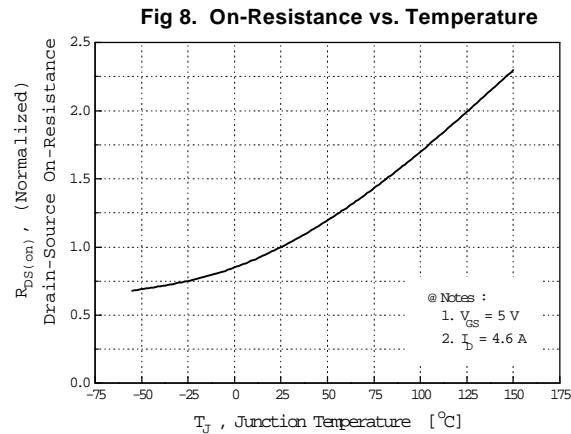
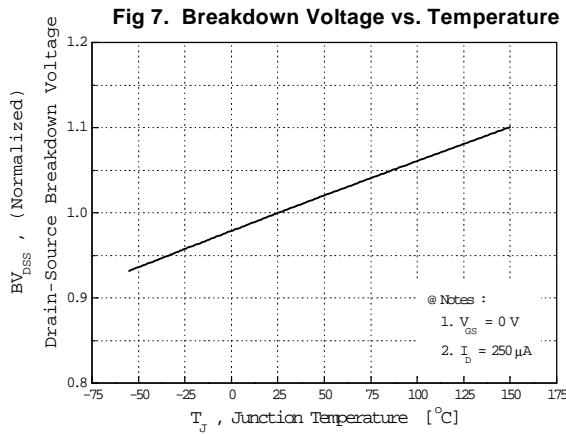


Fig 6. Gate Charge vs. Gate-Source Voltage



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Fig 12. Gate Charge Test Circuit & Waveform

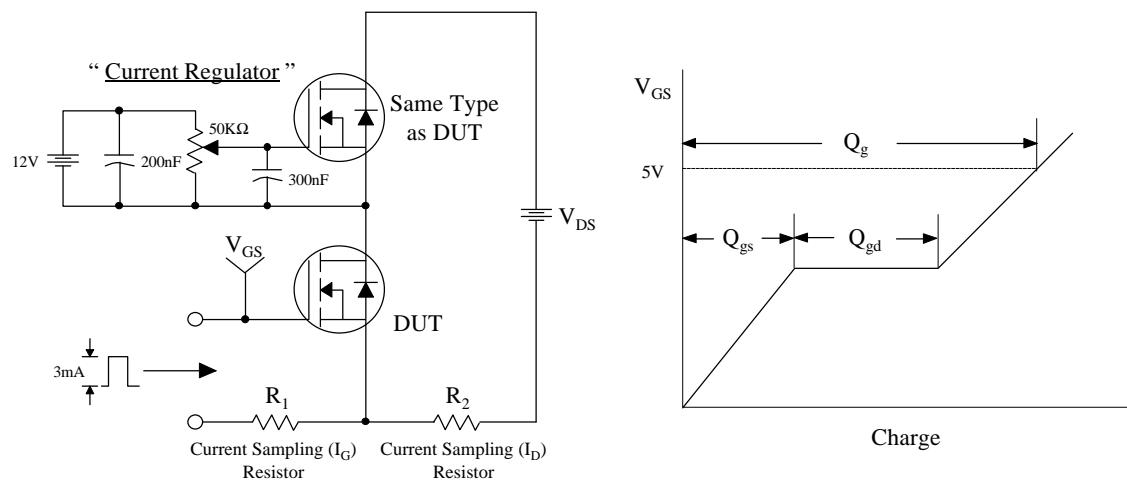


Fig 13. Resistive Switching Test Circuit & Waveforms

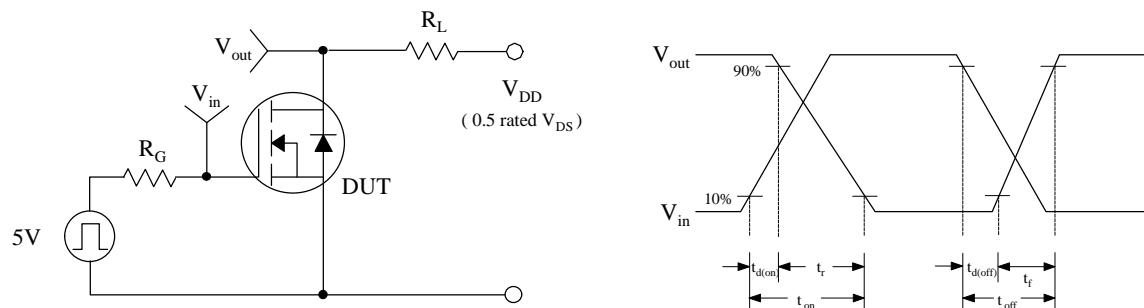
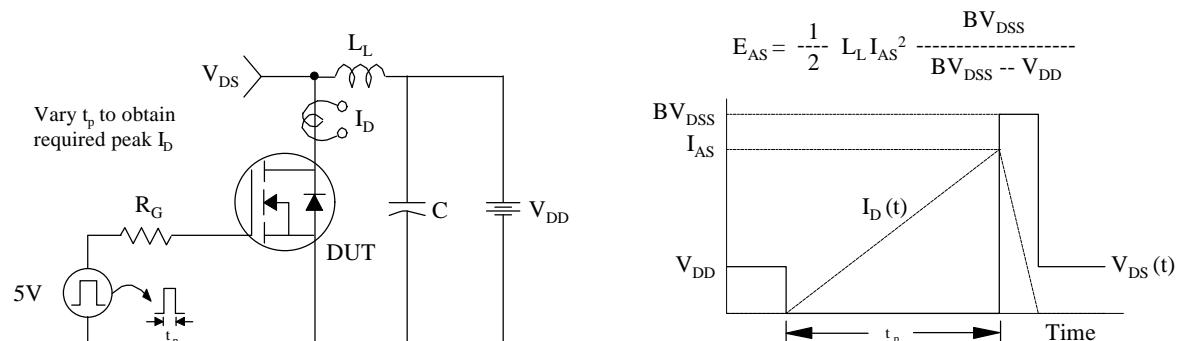


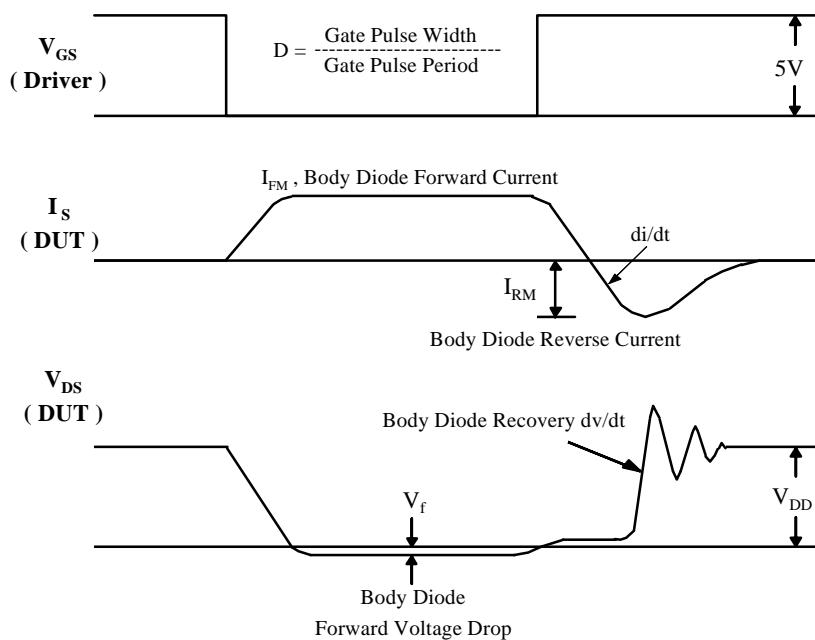
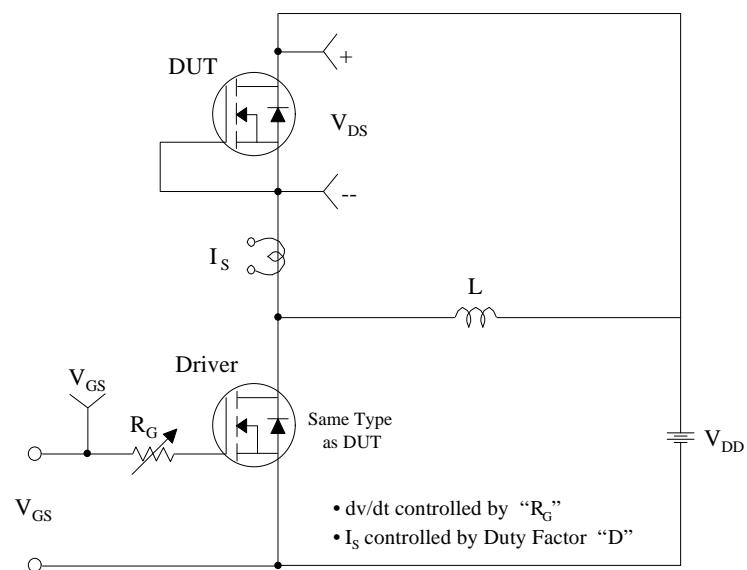
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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